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This diagram shows a cross-section of a multi-layer printed circuit board (PCB) assembly. The PCB consists of several layers, with the top layer (1) and bottom layer (2) being conductive. A central core or prepreg layer (3) is sandwiched between them. The assembly is supported by three vertical pillars (4). Various components are mounted on the top surface, including a component (5) with a solder joint (6), a component (7) with a solder joint (8), and a component (9) with a solder joint (10). A component (11) is also shown with a solder joint (12). The bottom surface of the PCB features a conductive layer (13) and a non-conductive layer (14). The entire assembly is shown in a cross-sectional view, highlighting the internal structure and the solder joints connecting the components to the PCB.

[illegible]

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FIG. 2A

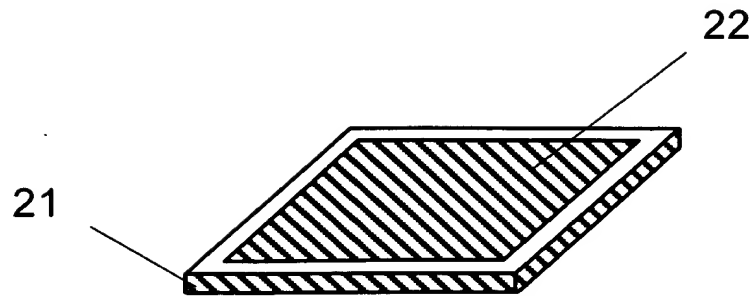


FIG. 2B

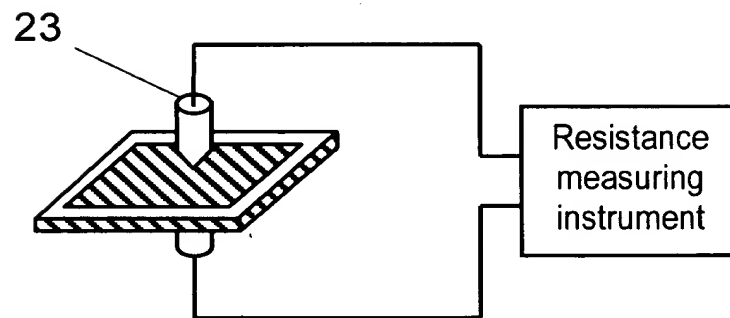


FIG. 2C

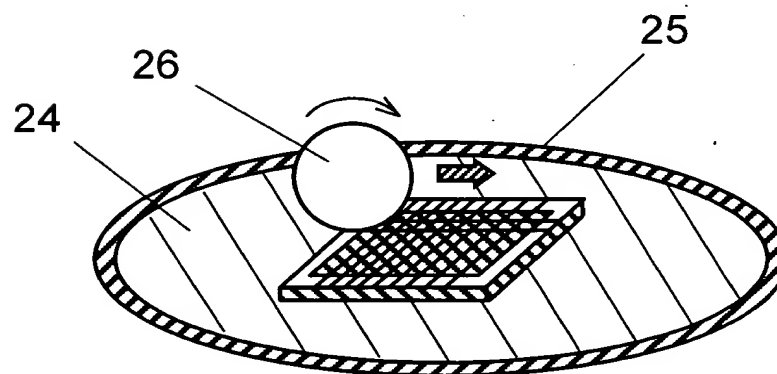


FIG. 3

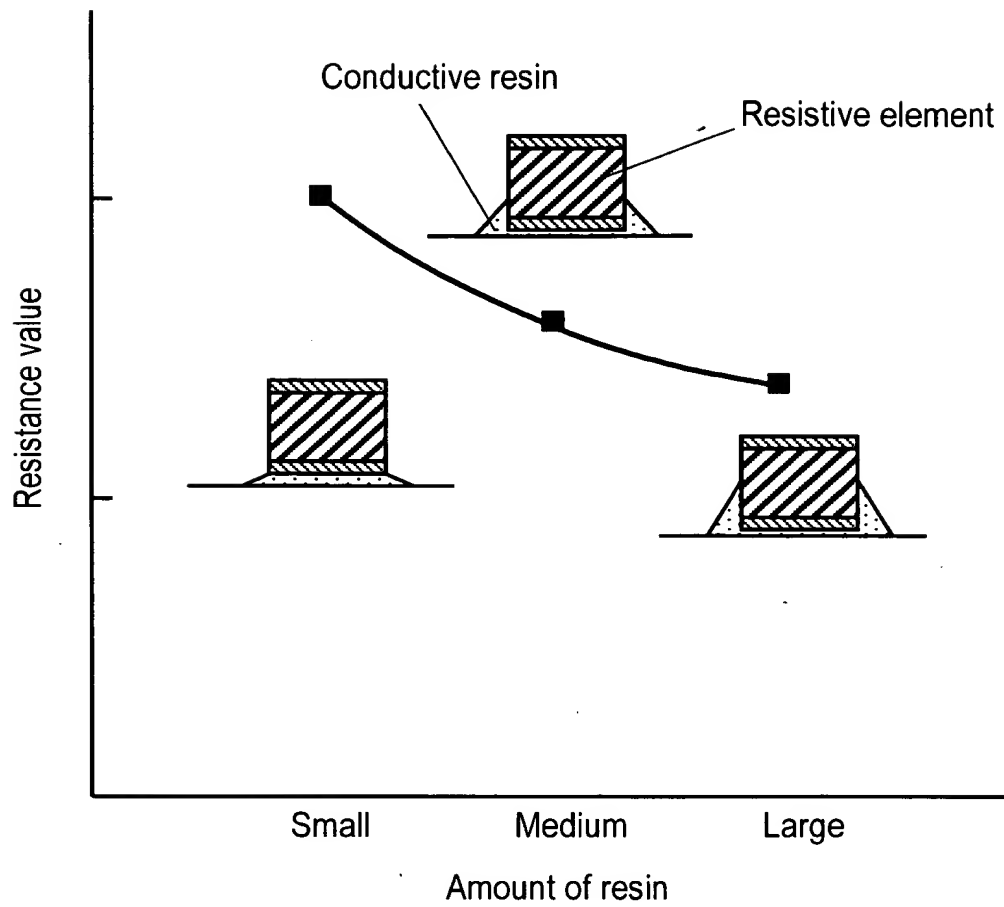


FIG. 4

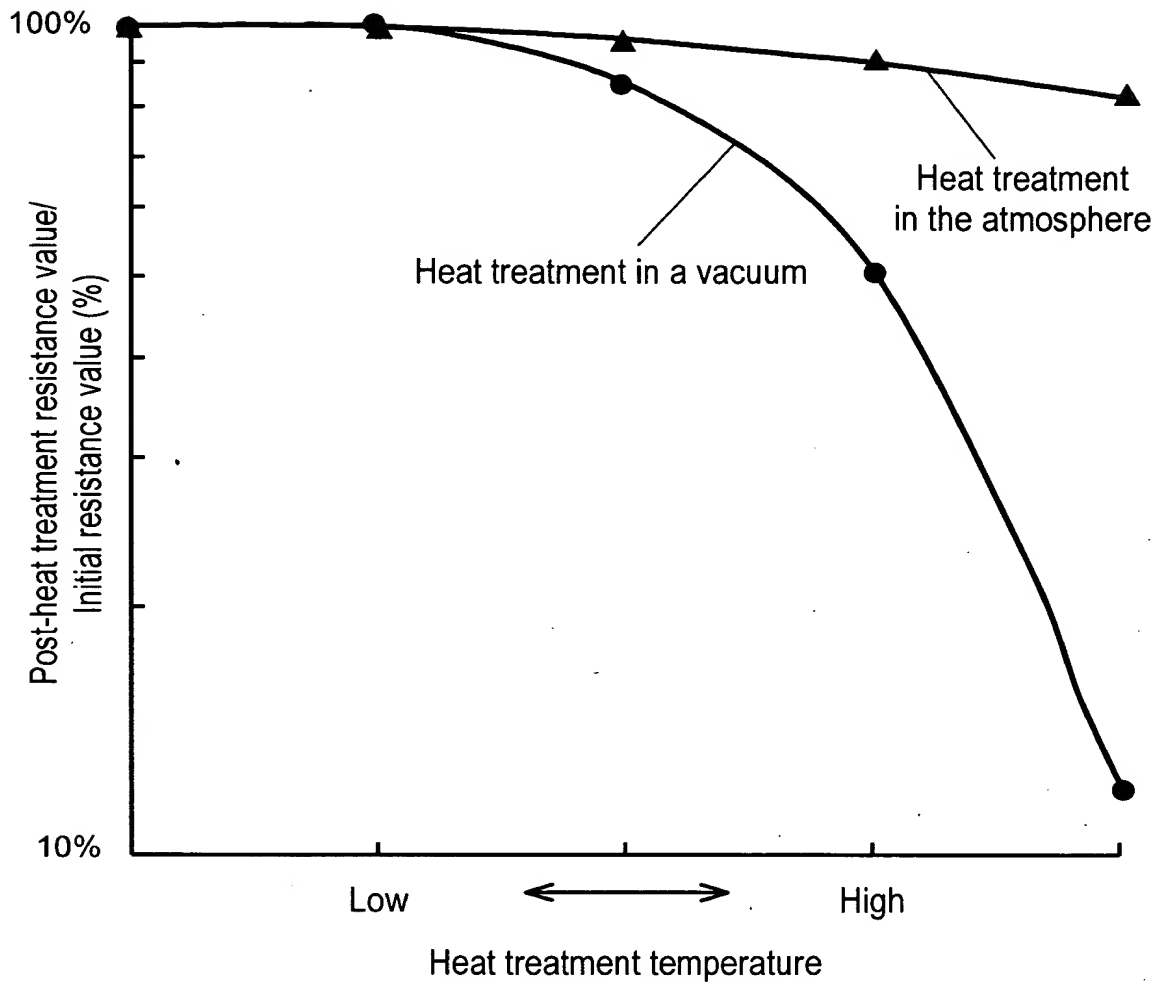


FIG. 5

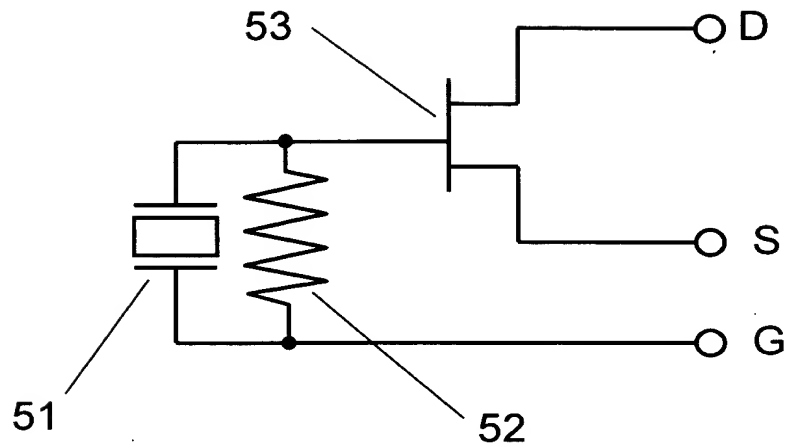


FIG. 6 PRIOR ART

